

10/575510

Customer No. 28289

Application No. Not Yet Assigned
Paper Dated April 13, 2006
In Reply to USPTO Correspondence of N/A
Attorney Docket No. 1217-060907

IAP9 Rec'd PCT/PTO 13 APR 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : Not Yet Assigned
Applicants : **Koichi NAGAMOTO et al.**
Filed : Concurrently Herewith
Title : **SURFACE-PROTECTING SHEET AND SEMICONDUCTOR WAFER LAPPING METHOD**
International Application No. : PCT/JP2004/015131
International Filing Date : 14 October 2004
Priority Date(s) Claimed : 16 October 2003

MAIL STOP PCT
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Sir:

Prior to initial examination, please amend the above-identified patent application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 this paper.

Remarks begin on page 8 of this paper.